

PRODUCT DATA SHEET

TACFlux® 483

Introduction

TACFlux® 483 is a no-clean flux formulated for SnPb solders. **TACFlux® 483** provides excellent wetting (air or nitrogen atmosphere) to many surfaces, including Ni. Its many uses include rework/repair and SMT component attach (including BGA and flip-chip). A minimum reflow temperature of approximately 200°C (dependent on reflow profile and method) is recommended to sufficiently drive off all volatiles for consideration in no-clean applications.

Properties

J-STD-004 (IPC-TM-650)	Result
Flux Type Classification	ROL1
Flux-Induced Corrosion (Copper Mirror)	Pass
Presence of Halide: – Silver Chromate – Fluoride Spot Test – Cl Equivalent	Pass Pass ~0.067%
Post-Reflow Flux Residue (ICA Test)	~48%
Typical Thixotropic Index (SSF)	~-0.86
SIR	Pass
Bellcore Electromigration	Pass
Acid Value	~98
Viscosity (Brookfield)	~500kcps
Specific Gravity	~1.1g/ml
Tack	~270g
Additional Test Results	
Appearance	Light yellow-amber
Maximum Reflow Temperature	300°C
Reflow Atmosphere	Nitrogen or air
Shelf Life	1 year
Storage Condition	Stored @ 0–30°C (tip down for syringe/cartridge)

All information is for reference only.
Not to be used as incoming product specifications.

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Packaging

TACFlux® 483 is available in 10 and 30cc syringes or 100g jars; however, other packaging can be provided to meet specific requirements.

Cleaning

TACFlux® 483 is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner.

Reflow

Peak reflow temperature should be <300°C in an air or nitrogen atmosphere.

Storage

TACFlux® 483 syringes and cartridges should be stored tip down at 0–30°C. If refrigerated, **TACFlux® 483** should be thawed for 4 hours at room temperature before using.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



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